

JUN 06 2002

**TRANSMITTAL LETTER
(General - Patent Pending)**

Docket No.
E0520CIP

In Re Application Of: **Kashmir S. Sahota, Diana M. Schonauer, Johannes F. Groschopf, Gerd F.C. Marxsen, Steven A. Avanzino**

Serial No.
09/749,191

Filing Date
December 26, 2000

Examiner
L. Umez-Eronini

Group Art Unit
1765

Title: **"PREVENTION OF PRECIPITATION DEFECTS ON COPPER INTERCONNECTS DURING CMP BY USE SOLUTIONS CONTAINING ORGANIC COMPOUNDS WITH SILICA ADSORPTION AND COPPER CORROSION INHIBITING PROPERTIES"**

TO THE ASSISTANT COMMISSIONER FOR PATENTS:

Transmitted herewith is:

**Amendment Transmittal Letter (in duplicate)
Amendment and Response to Office Action (11 pp)
Return Receipt Postcard**

COPY OF PAPERS
ORIGINALLY FILED

in the above identified application.

- ☒ No additional fee is required.
- ☐ A check in the amount of _____ is attached.
- ☒ The Assistant Commissioner is hereby authorized to charge and credit Deposit Account No. **01-0365** as described below. A duplicate copy of this sheet is enclosed.
- ☐ Charge the amount of _____
- ☒ Credit any overpayment.
- ☒ Charge any additional fee required.

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TC 1700

Deborah W. Wenocur
Signature

Dated: May 26, 2002

**Deborah W. Wenocur, Reg. No. 40,221
Agent for Applicant
Advanced Micro Devices, Inc.
Technology Law Dept. M/S 68
One AMD Place
P.O. Box. 3453
Sunnyvale, CA 94088-3453**

I certify that this document and fee is being deposited on May 23, 2002 with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

Deborah W. Wenocur
Signature of Person Mailing Correspondence

Deborah W. Wenocur

Typed or Printed Name of Person Mailing Correspondence

CC:

AMENDMENT TRANSMITTAL LETTER (Large Entity)

Applicant(s): K. Sahota, D. Schonauer, J. Groschopf, G. Marxsen, and S. Avanzino

Docket No.

E0520CIP

Serial No.

09/749,191

Filing Date

December 26, 2000

Examiner

L. Umez Eronini

Group Art Unit

1765

Invention: Prevention of Precipitation Defects on Copper Interconnects During CMP by Use of Solutions Containing Organic Compounds with Silica Adsorption and Copper Corrosion Inhibiting Properties

TO THE ASSISTANT COMMISSIONER FOR PATENTS:

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

CLAIMS AS AMENDED

	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FOR	NUMBER EXTRA CLAIMS PRESENT	RATE	ADDITIONAL FEE
TOTAL CLAIMS	71 -	73 =	0 x	\$18.00	\$0.00
INDEP. CLAIMS	5 -	5 =	0 x	\$84.00	\$0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					\$0.00
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$0.00

☒ No additional fee is required for amendment.

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☒ Any additional filing fees required under 37 C.F.R. 1.16.

☒ Any patent application processing fees under 37 CFR 1.17.

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Deborah W. Wenocur, Reg. No. 40,221

Agent for Applicant

Advanced Micro Devices, Inc., Technology Law Dept.

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Sunnyvale, CA 94088-3453

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